



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSZ021N04LS6	Issued	17. April 2021
MA#	MA005421778		
Package	PG-TSDSON-8-36	Weight*	35.74 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.723	2.02	2.02	20242	20242
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		103	
	non noble metal	zinc	7440-66-6	0.015	0.04		410	
	non noble metal	iron	7439-89-6	0.293	0.82		8202	
	non noble metal	copper	7440-50-8	11.903	33.30	34.17	333049	341764
wire	noble metal	gold	7440-57-5	0.028	0.08	0.08	784	784
encapsulation	organic material	carbon black	1333-86-4	0.034	0.10		962	
	plastics	epoxy resin	-	1.582	4.43		44269	
	inorganic material	silicondioxide	60676-86-0	15.581	43.61	48.14	435948	481179
leadfinish	non noble metal	tin	7440-31-5	0.420	1.18	1.18	11764	11764
plating	noble metal	silver	7440-22-4	0.003	0.01	0.01	88	88
solder	noble metal	silver	7440-22-4	0.024	0.07		671	
	non noble metal	tin	7440-31-5	0.048	0.13		1342	
	non noble metal	lead	7439-92-1	0.887	2.48	2.68	24828	26841
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			35	
	non noble metal	zinc	7440-66-6	0.005	0.01		141	
	non noble metal	iron	7439-89-6	0.101	0.28		2816	
	non noble metal	copper	7440-50-8	4.087	11.43	11.72	114346	117338
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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